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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/816,559	03/30/2004	Yew Wee Cheong	111079-136359	1225
31817	7590 05/25/2006		EXAM	INER
	, WILLIAMSON & W ENTER, SUITE 1900	SHAKERI, HADI		
1211 S.W. FI	· ·		ART UNIT	PAPER NUMBER
PORTLAND,	OR 97204		3723	

DATE MAILED: 05/25/2006

Please find below and/or attached an Office communication concerning this application or proceeding.

J.S. Patent and Trademark Office PTOL-326 (Rev. 7-05) Office Ac	ction Summary	Part of Paper No./Mail Date 0	51706
Notice of Draftsperson's Patent Drawing Review (PTO-948)     Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)     Paper No(s)/Mail Date	Paper No	(s)/Mail Date Informal Patent Application (PTO-152)	
Attachment(s)  1) Notice of References Cited (PTO-892)	4) ☐ Interview	Summary (PTO-413)	
and all all all all all all all all all al	o, are coranea copies ne		
application from the International Bureau  * See the attached detailed Office action for a list	, , , , , ,	t received	
3. Copies of the certified copies of the prior	•	n received in this National Stage	)
2. Certified copies of the priority document		Application No	
1. Certified copies of the priority document	s have been received.		
<ul><li>12) Acknowledgment is made of a claim for foreign</li><li>a) All b) Some * c) None of:</li></ul>	priority under 35 U.S.C.	§ 119(a)-(d) or (f).	
Priority under 35 U.S.C. § 119			
11) The oath or declaration is objected to by the Ex	caminer. Note the attache	ea Office Action of form PTO-152	۷.
Replacement drawing sheet(s) including the correct			
Applicant may not request that any objection to the	- · ·		- 4 4 55
10)⊠ The drawing(s) filed on 30 March 2006 is/are:	a)⊠ accepted or b)⊡ ol	ojected to by the Examiner.	
9)⊠ The specification is objected to by the Examine	er.		
Application Papers			
8) Claim(s) are subject to restriction and/o	r election requirement.		
7) Claim(s) is/are objected to.			
6)⊠ Claim(s) <u>1-25</u> is/are rejected.			
5) Claim(s) is/are allowed.			
4a) Of the above claim(s) is/are withdraw			
4)⊠ Claim(s) <u>1-25</u> is/are pending in the application.			
Disposition of Claims			
closed in accordance with the practice under E	Ex parte Quayle, 1935 C.	D. 11, 453 O.G. 213.	
3) Since this application is in condition for alloward	nce except for formal ma	tters, prosecution as to the merit	ts is
2a)⊠ This action is <b>FINAL</b> . 2b)☐ This	action is non-final.		
1) Responsive to communication(s) filed on			
Status			
A SHORTENED STATUTORY PERIOD FOR REPL' WHICHEVER IS LONGER, FROM THE MAILING D.  Extensions of time may be available under the provisions of 37 CFR 1.1 after SIX (6) MONTHS from the mailing date of this communication.  If NO period for reply is specified above, the maximum statutory period v. Failure to reply within the set or extended period for reply will, by statute Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	ATE OF THIS COMMUN 36(a). In no event, however, may a will apply and will expire SIX (6) MO c, cause the application to become a	ICATION. The reply be timely filed ENTHS from the mailing date of this communication (ABANDONED (35 U.S.C. § 133).	
Period for Reply	VIC CET TO EVOIDE A	MONTHYON OR THIRTY (20) DA	VC
The MAILING DATE of this communication app	pears on the cover sheet	with the correspondence address	
-	Hadi Shakeri	3723	
Office Action Summary	Examiner	Art Unit	
	10/816,559	CHEONG, YEW WEE	
	Application No.	Applicant(s)	

#### **DETAILED ACTION**

# Specification

1. The abstract of the disclosure does not commence on a separate sheet in accordance with 37 CFR 1.52(b)(4). A new abstract of the disclosure is required and must be presented on a separate sheet, apart from any other text.

# Claim Rejections - 35 USC § 112

2. The following is a quotation of the second paragraph of 35 U.S.C. 112:

The specification shall conclude with one or more claims particularly pointing out and distinctly claiming the subject matter which the applicant regards as his invention.

- 3. Claims 1-25 are rejected under 35 U.S.C. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.
- 4. Claim1, recites for "cutting and severing a semiconductor wafer...in a manner... as if the semiconductor wafer had not been cut" rendering the claim indefinite because it is unclear what the step recited covers. "Cutting and severing" as defined by the dictionary is in contradiction to "in a manner as if the wafer had not been cut". Merriam Webster dictionary defines "severing" as to put or keep apart: to remove (as a part) by or as if by cutting: to become separated, and it further defines "cutting" as to divide into parts with an edged tool: to separate or discharge from an organization: to single out and isolate: to change the direction of sharply: to divide into segments, therefore it is unclear whether the wafer is cut or not. Specification as originally filed describes "partial cutting", however this recitation (as part of original claim) is now amended to cutting and severing as if the workpiece had not been cut. Therefore a wafer, which has not been cut, may read over the step, as would a wafer that had been completely cut or a wafer that had been partially cut. The language as written does not clearly present the boundaries of the claim.

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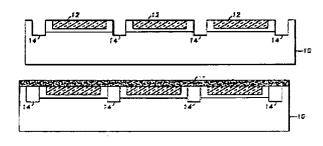
## Claim Rejections - 35 USC § 102

5. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

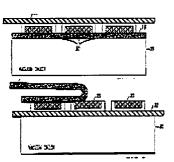
A person shall be entitled to a patent unless -

- (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.
- 6. Claims 1, 4, 5, 7, 17, and 20 (as best understood) are rejected under 35 U.S.C. 102(b) as being anticipated by Riding et al. (6,083,811).

Riding et al. meets all of the limitations of claims 1 and 17 (as best understood), i.e., at least partially cutting (14) a wafer (10); applying a tape (16) to the front side (8) and grinding the back side (6) (04:1-5)



Regarding claims 4, 5, 7, and 20, Riding et al. meets all of the limitations, i.e., mounting the grinded wafer and removing the protective tape; attaching adhesive (22) to the backside of the wafer; mounting the wafer before cutting it (03:44-50); wherein a vacuum transfer device may be used to move the wafer; and wherein the cut is sufficient to prevent cracking.



### Claim Rejections - 35 USC § 103

- 7. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
  - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the

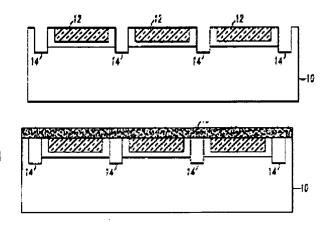
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invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

8. Claims 2, 3, 18 and 19 (as best understood) are rejected under 35 U.S.C. 103(a) as being unpatentable over Riding et al. (6,083,811) in view of Applicant's Admitted Prior Art (AAPA).

Riding et al. meets all of the limitations of the claims (as best understood), i.e., except for disclosing laser scribing and dicing the wafer and for disclosing for the wafer to include low-K interlayer dielectric layer, but as indicated by Applicant, e.g., page 6, lines 3-7, it is known in the art for low-K wafer to first laser scribe the



wafer and then saw cut it. It would have been obvious to one of ordinary skill in the art, at the time the invention was made, to modify the above method by laser scribing and saw cutting in view of AAPA to prevent cracking for wafers having ILD layers.

9. Claims 6, 8, 11-16 and 21-25 (as best understood) are rejected under 35 U.S.C. 103(a) as being unpatentable over Riding et al. in view of Inuzuka (6,777,310).

Riding et al. as modified in view of AAPA, above meets all of the limitations of the above claims (as best understood), except for disclosing cutting the protective tape and the adhesive around the wafer. Cutting the tape to the shape of the wafer is known as evident by Inuzuka. It would have been obvious to one of ordinary skill in the art, at the time the invention was made, to modify the method of Riding et al. by cutting the tapes to the shape of the wafer as taught by Inuzuka for ease of manufacturing or cost reduction.

The modified method (Riding in view of Inuzuka) meets all of the limitations of claims 8, 11-16 and 21-23 as indicated above, regarding claims 24 and 25, lacking limitations to define a wafer frame, chuck (30) as in Fig. 6 of Riding et al. is considered to meet the limitations, however, placing the grinded wafer on any frame to remove the protective tape would be obvious to one of ordinary skill in the art, depending on the operational parameters, e.g., on an assembly line, or the next step in the process.

#### Conclusion

**10. THIS ACTION IS MADE FINAL.** Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of this final action.

## Response to Arguments

11. Applicant's arguments filed March 14, 2006 have been fully considered but they are not persuasive. The argument that the amended claims are for grinding a semiconductor wafer is not persuasive, since firstly applicant claims a "method" and secondly the method as disclosed by Riding et al. meets the limitations as best understood as indicated above and in the previous Office Action. It is unclear how a "forming grooves" by Riding et al. as admitted by Applicant

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does not meet the recitation of "cutting... as if uncut". Riding et al. partially cuts the wafer prior to grinding meeting the limitations of the independent claims as recited.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Hadi Shakeri whose telephone number is (571) 272-4495. The examiner can normally be reached on Monday-Friday.

The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Hadi Shakeri Primary Examiner Art Unit 3723

May 17, 2006